

Description

The SX180N08T uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 10V.

This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 85V$ $I_D = 180A$

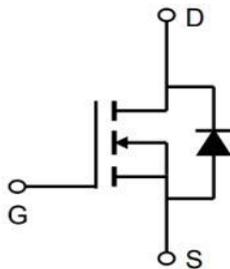
$R_{DS(ON)} < 3.5m\Omega$ $V_{GS}=10V$

Application

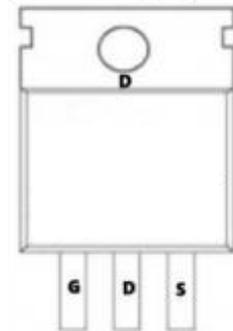
Battery protection

Load switch

Uninterruptible power supply



TO-263-3L



Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	85	V
V _{GS}	Gate-Source Voltage	±20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, V_{GS} @ 10V	180	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, V_{GS} @ 10V	100	A
IDM	Pulsed Drain Current	480	A
EAS	Single Pulse Avalanche Energy	1558	mJ
$P_D@T_C=25^\circ C$	Total Power Dissipation ⁴	284	W
TSTG	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C
R _{θJA}	Thermal Resistance Junction-Ambient	0.53	°C/W
R _{θJC}	Thermal Resistance Junction-Case	48	°C/W

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V(BR)DSS	Drain-source breakdown voltage	V _{GS} =0V, I _D =250uA	85	92		V
V _{GS(th)}	Gate threshold voltage	V _{DS} =V _{GS} , I _D =250uA T _J =25°C	2.0	3.0	4.0	V
IDSS	Zero gate voltage drain current	V _{DS} =80V, V _{GS} =0V T _J =25°C	-		1	μA
IDSS	Zero gate voltage drain current	V _{DS} =80V, V _{GS} =0V T _J =125°C		- 5		μA
IGSS	Gate-source leakage current	V _{GS} =20V, V _{DS} =0V	-	-	100	nA
RDS(on)	Drain-source on-state resistance	V _{GS} =10V, I _D =50A, T _J =25°C	-	2.9	3.5	mΩ
gfs	Transconductance	V _{DS} =5V, I _D =40A	-	106	-	S
Ciss	Input Capacitance	V _{GS} =0V, V _{DS} =40V, f=1MHz	-	6813	-	pF
Coss	Output Capacitance		-	808	-	pF
Crss	Reverse Transfer Capacitance		-	48	-	pF
Q _G	Gate Total Charge	V _{GS} =10V, V _{DS} =40V, I _D =25A	-	91	-	nC
Q _{GS}	Gate-Source charge		-	37	-	nC
Q _{GD}	Gate-Drain charge		-	25	-	nC
td(on)	Turn-on delay time	T _J =25°C, V _{GS} =10V, V _{DS} =40V, R _L =3Ω	-	38	-	ns
t _r	Rise time		-	58	-	ns
td(off)	Turn-off delay time		-	63	-	ns
t _f	Fall time		-	32	-	ns
R _G	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	2	-	Ω
VSD	Body Diode Forward Voltage	V _{GS} =0V, I _{SD} =50A	-	0.85	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A, dI/dt=500A/μs	-	85	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	313	-	nC

Note :

- 1、 The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、 The test cond ≅ 300us duty cycle ≅ 2%, duty cycle ition is V_{DD}=64V_{GS}=10V, L=0.1mH, I_{AS}=53.8A
- 4、 The power dissipation is limited by 175°C junction temperature
- 5、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

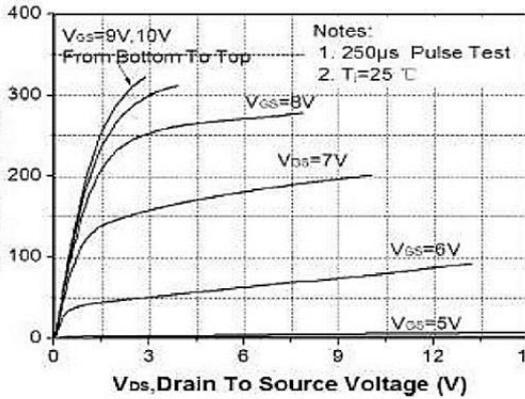


Figure 1. Typ. Output Characteristics ($T_j=25^\circ\text{C}$)

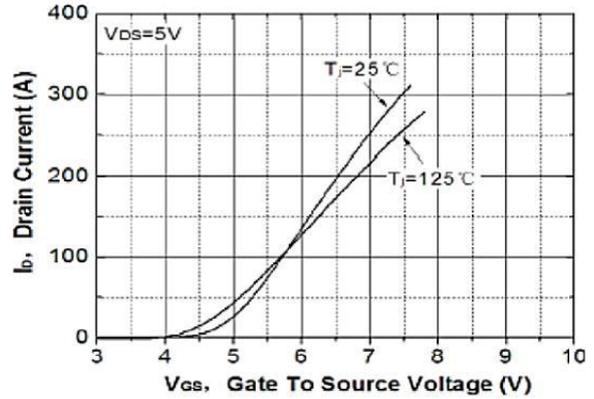


Figure 2. Transfer Characteristics

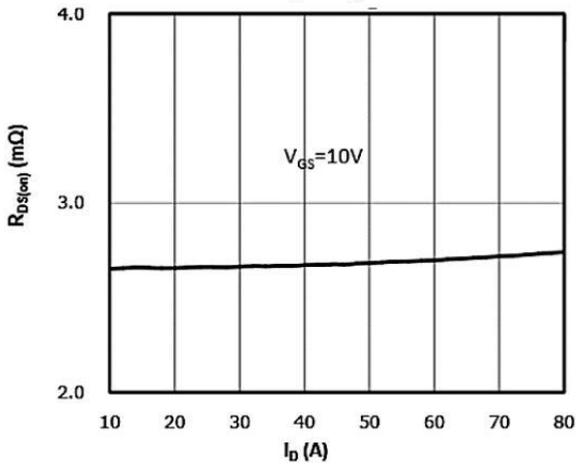


Figure 3. On-Resistance vs. Drain Current and Gate Voltage Figure

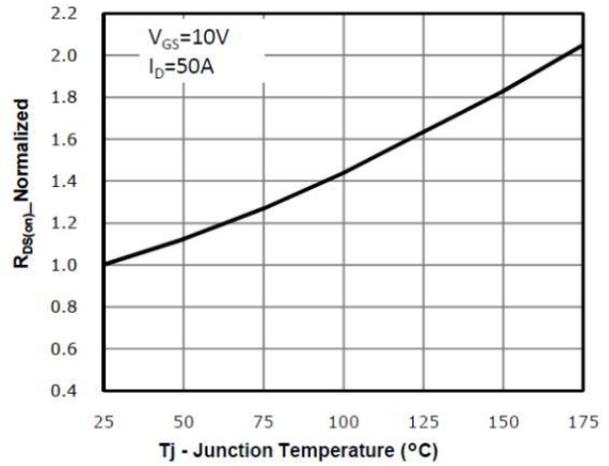


Figure 4. On-Resistance vs. Junction Temperature

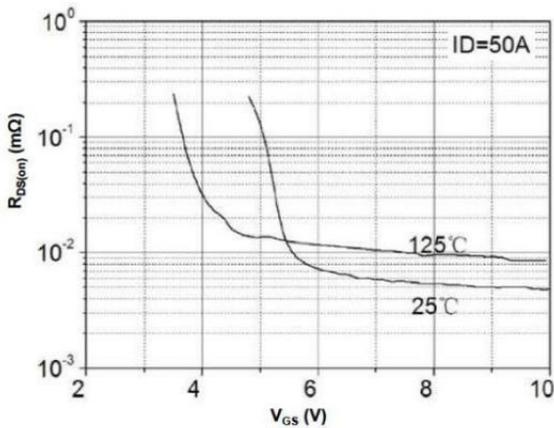


Figure 5. On-Resistance vs. Gate-Source Voltage

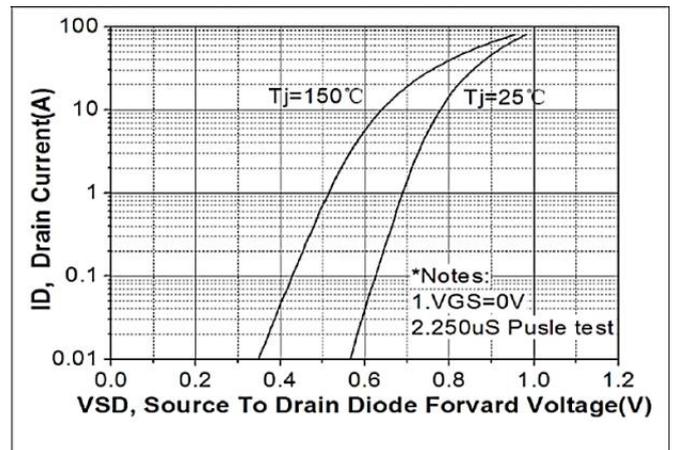


Figure 6. Body-Diode Characteristics

Typical Characteristics

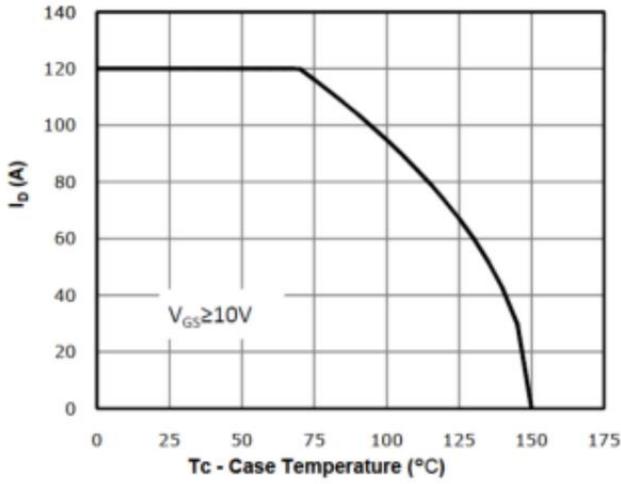


Figure 7. Gate-Charge Characteristics

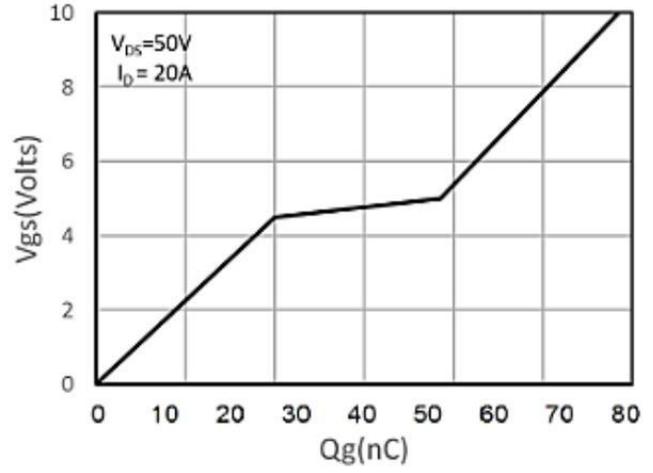


Figure 8. Drain Current Derating

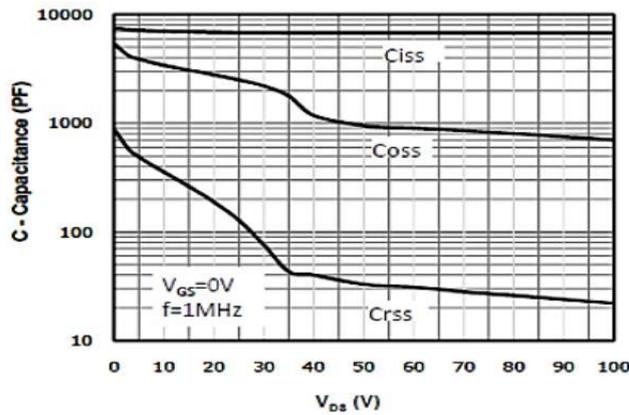


Figure 9: Normalized Maximum Transient Thermal Impedance

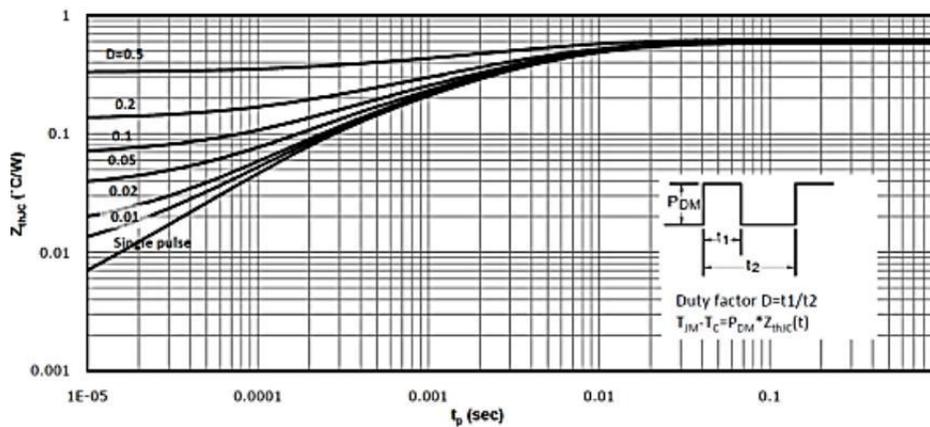
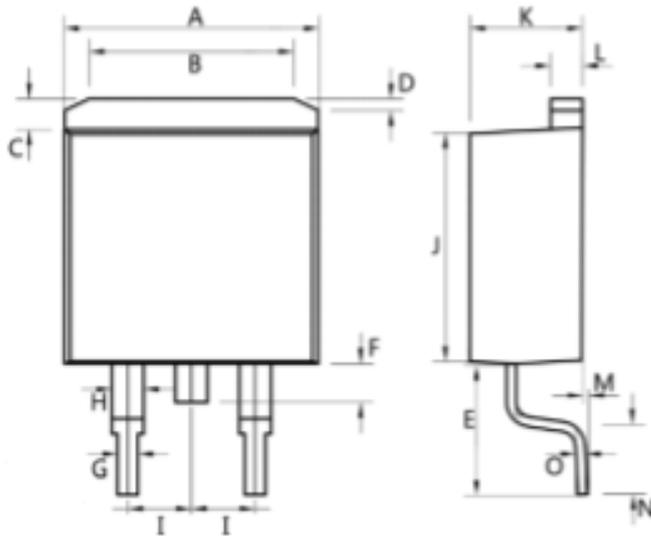


Figure 10. Capacitance Characteristics

Package Mechanical Data- TO-263-3L



Dim.	Min.	Max.
A	10.0	10.5
B	7.25	7.75
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.75	0.95
H	1.15	1.35
I	Typ 2.54	
J	8.4	8.6
K	4.4	4.6
L	1.25	1.45
M	0.02	0.1
N	2.4	2.8
O	0.35	0.45
All Dimensions in millimeter		

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-263-3L		800